

Emismitted herewith for filing is the Patent Application of:

Sir:

METHOD OF FORMING METAL-INSULATOR-METAL (MIM) CAPACITORS AT COPPER PROCESS

O.		·				0	
Enclosed are:							
x	6 sheets of drawing(s) - formal. An assignment of the invention to Taiwan Semiconductor Manufacturing Co.						
x	An assignment of the invention to Taiwan Semiconductor Manufacturing Co.						
	An associate power of attorney Applicant claims small entity status						
	Request & Certification under 35 USC 122(b)(2)(b)(i)						
The filin	g fee has been	calculated as shown bel	low:		1		
		(Col. 1)	(Col. 2)	OTHER THAN	A SMALL ENTITY		
FOR:		NO. FILED	NO. EXTRA	RATE	FEE		
BASIC	FEE	><	\nearrow		\$ 770.		
TOTAL	L CLAIMS	30 -20=	10	x 18 =	\$ 180.		
INDEP	CLAIMS	3 -3=	0	x 86 =	\$ 0,		
				SUB TOTAL	\$ 950.		
				ASSIGNMENT	\$40.		
	·			TOTAL	\$ 990.		
x x	Please charge my Deposit Account No. 19-0033 in the amount of \$ 990. A duplicate copy of this sheet is enclosed.					losed.	
	The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any						
	overpayment	verpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.					
	X A	X Any additional filing fees required under 37 CFR §1.16.					
	X A	X Any patent application processing fees under 37 CFR §1.17.					
		A 1	_	Respectfully submitted,			
		1AN, REG. NO. 37,761					
_			EXPRE	SS MAIL CERTIFICATE			

Express Mail No.EV313927953US

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Assistant Commissioner of Patents, Alexandria, VA, 22313-1450. Applicant and/of Attorney requests the date of deposit as the Filing Date.